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843.37558VX1
Response Under 37 CFR 1.116
Expedited Procedure
Group No.: 2825

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	**M. FUNABASHI**
Application No.:	**09/902,673**
Filed:	**July 12, 2001**
For:	**METHOD OF MANUFACTURING A SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE**
Art Group:	**2825**
Examiner:	**L. Malsawma**

AMENDMENT AFTER FINAL REJECTION

ATTN: BOX AF
Commissioner for Patents
Washington, D.C. 20231

January 29, 2003

Sir:

In response to the Office Action mailed July 29, 2002, the time period for responding having been extended until January 29, 2003, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claim 31 without prejudice or disclaimer, and add the following new claim to the application:

--33. A method of manufacturing a semiconductor integrated circuit device according to claim 20, wherein said processing solution etches the silicon oxide but does not etch the silicon wafer.--

Do not Enter